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Http://www.ledtech.com.tw

SPECIFICATION

PART NO.: LT5K63-3R-UJF7-SA8

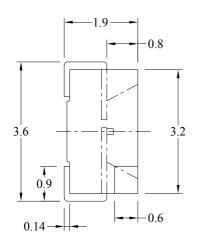
3.2 x 2.8mm SMD TYPE

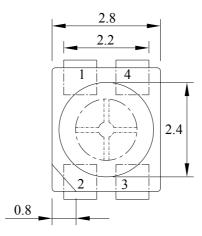


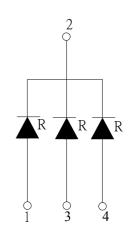
Approved by	Checked by	Prepared by
Tung	Lian	Show



Package Dimensions







Notes:

- 1. All dimensions are in mm.
- 2. Tolerance is ± 0.25 mm unless otherwise noted.

Description

	LED Chip			
Part No.	Material	Emitting Color	Lens Color	
LT5K63-3R-UJF7-SA8	AlGaInP/Si	Hyper Red	Water Clear	

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Absolute Maximum Ratings at $Ta=25^{\circ}C$:

Parameter	Symbol	Rating	Unit
Power Dissipation ★	PD	78	mW
Reverse Voltage ★	VR	5	V
D.C. Forward Current ★	If	30	mA
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.) ★	If(Peak)	100	mA
Operating Temperature Range	Topr.	-25 to +85	$^{\circ}\! \mathbb{C}$
Storage Temperature Range	Tstg.	-40 to +100	$^{\circ}$
Soldering Temperature ★	Tsld.		for 10 sec.

[★] The value are based on 1 die performance.

Electrical and Optical Characteristics:

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Luminous Intensity ★2	Iv	If=20mA ★1	756	1250		mcd
Forward Voltage★1	Vf	If=20mA★1		2.1	2.6	V
Peak Wavelength★1	λр	If=20mA★1		632		nm
Dominant Wavelength★1	λd	If=20mA★1		625		nm
Reverse Current ★1	Ir	Vr=5V ★ 1			100	μΑ
Viewing Angle★2	2 \theta 1/2	If=20mA★1		120		deg
Spectrum Line Halfwidth★1	Δλ	If=20mA★1		20		nm

Notes: 1.The datas tested by IS tester.

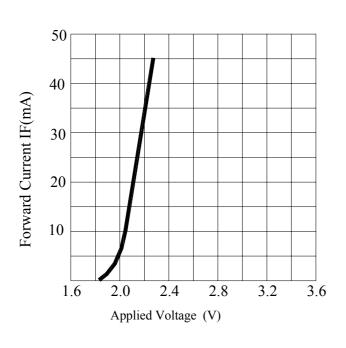
- 2. Customer's special requirements are also welcome.
- 3. ★1 For each die
- 4. ★2 When all LED dies are operated simultaneously..

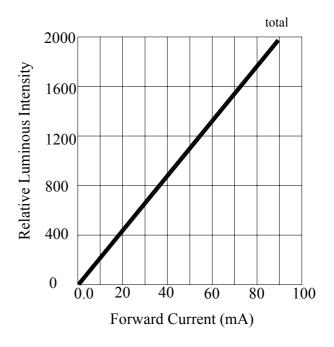
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Typical Electrical/Optical Characteristic Curves

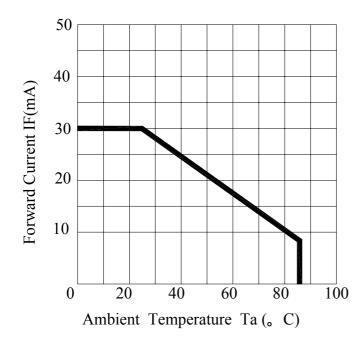
(25°C Ambient Temperature Unless Otherwise Noted)

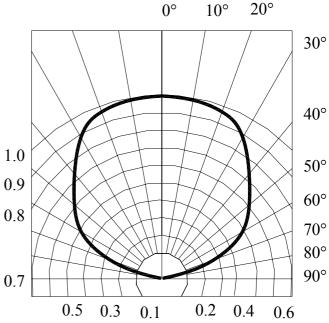




Forward Current VS. Applied Voltage

Forward Current VS. Luminous Intensity





Ambient Temperature VS. Forward Current

Radiation Diagram

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PRECAUTION IN USE

Storage

Recommended storage environment

Temperature: $5^{\circ}\text{C} \sim 30^{\circ}\text{C} (41^{\circ}\text{F} \sim 86^{\circ}\text{F})$

Humidity: 60% RH Max.

Use within 7 days after opening of sealed vapor/ESD barrier bags.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours.

Fold the opened bag firmly and keep in dry environment.

Soldering

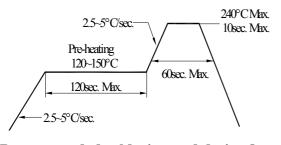
Reflow Soldering			Hand Soldering		
	Lead Solder	Lead – free Solder			
Pre-heat	120~150°C	180~200°C	Temperature	350°C Max.	
Pre-heat time	120sec. Max.	120sec. Max.	Soldering time	3sec. Max.	
Peak temperature	240°C Max.	260°C Max.		(one time only)	
Soldering time	10sec. Max.	10sec. Max.			
Condition	refer to	refer to			
	Temperature-	Temperature-			
	profile 1	profile 2			

^{*}After reflow soldering rapid cooling should be avoided.

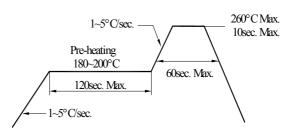
[Temperature-profile (Surface of circuit board)]

Use the conditions shown to the under figure.

<1: Lead Solder>

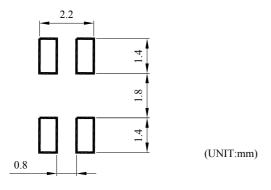


<2: Lead-free Solder>



Recommended soldering pad design]

Use the following conditions shown in the figure.



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Handling of Silicone Resin LEDs

Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound



Figure 1

In general, LEDs should only be handled from the side. By the way, this also applies to LEDs without a silicone sealant, since the surface can also become scratched.

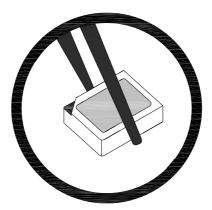


Figure 2

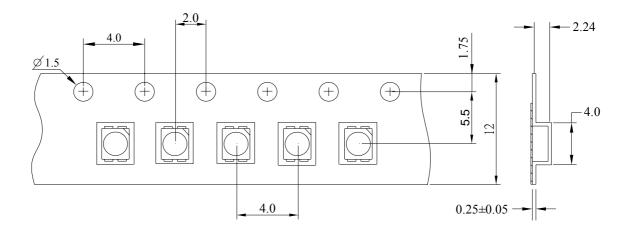
When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented.

This is assured by choosing a pick and place nozzle which is larger than the LED's reflector area.

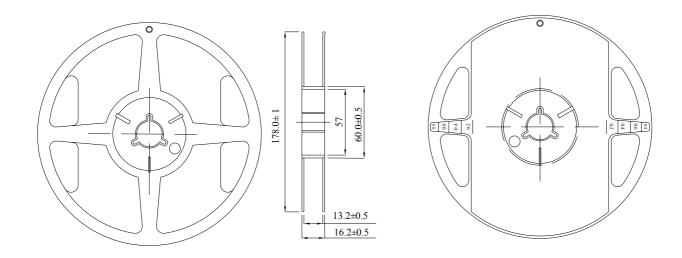
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Dimensions for Tape



Dimensions for Reel



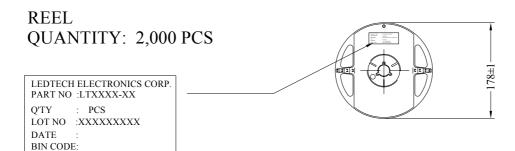
Notes:

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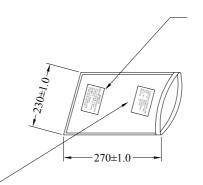


Packing



BAG QUANTITY: 2,000 PCS

LEDTECH ELECTRONICS CORP. PART NO :LTXXXX-XX Q'TY · PCS LOT NO :XXXXXXXXX DATE BIN CODE:

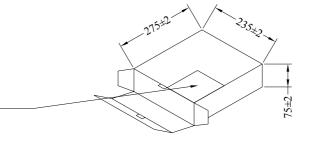


溼氣敏感材料 MOISTURE SENSITIVE DEVICES

- MOISTORE SENSITIVE DEVICE
 . たぎC-30°C :
 2. 開封後需在168小時內使用。
 Devices have to be mounted within 168 hours after this bag is opened.

INSIDE BOX QUANTITY: 4 BAGS TOTAL: 8,000 PCS

LEDTECH ELECTRONICS CORP. PART NO :LTXXXX-XX PCS LOT NO :XXXXXXXXX DATE BIN CODE:



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